

SECTION II—CLAIMS

1.-12. (Canceled)

13. (Original) A process of forming an oscillator comprising:

providing an oscillator member;

determining a first resonant frequency of the oscillator member;

patterning at least one structure on the oscillator member; and

determining a second resonant frequency of the oscillator member.

14. (Original) The process according to claim 13, before patterning further comprising:

forming a protective layer over the oscillator member.

15. (Original) The process according to claim 13, wherein patterning, further comprising:

directing radiant energy at the oscillator member.

16. (Original) The process according to claim 13, wherein patterning, further comprising:

directing radiant energy at the oscillator member; and

removing at least one structure from the oscillator member.

17. (Original) The process according to claim 13, wherein patterning, further comprising:

directing radiant energy at the oscillator member; and

precipitating a vapor on the oscillator member.

18. (Currently Amended) The process according to claim [[13]] 15, wherein the radiant energy source is selected from a focused ion beam and a laser.

19. (Original) The process according to claim 13, wherein patterning further comprises:

continuously monitoring the resonant frequency from the first frequency to the second frequency by vibrating the oscillator member.

20. (Original) The process according to claim 13, wherein patterning is repeated to form an empirical spaced-apart stack pattern, further comprising:

determining the second resonant frequency of the oscillator member; and

forming the empirical spaced-apart stack pattern upon a second oscillator member.

21-28. (Canceled)